

AZ nLOF 2035 – run sheet

Merck

[nanyte.com/photoresists/az-nlof-2035](https://www.merck.com/photonics/az-nlof-2035) · last updated 2026-07-26

Thickness: 3–6.1 μm

Softbake: 110 °C (100–110 °C) · 60 s · hotplate

Exposure dose: 80 mJ/cm² @ 365 nm

Post-exposure bake: 110 °C (100–115 °C) · 60 s

Develop: Developer AZ 300MIF · Dilution used as supplied (ready-to-use MIF developer; industry-standard 0.26N/2.38% TMAH per DEVELOPING section) · Time 2 min · Method puddle